

FIG. 1



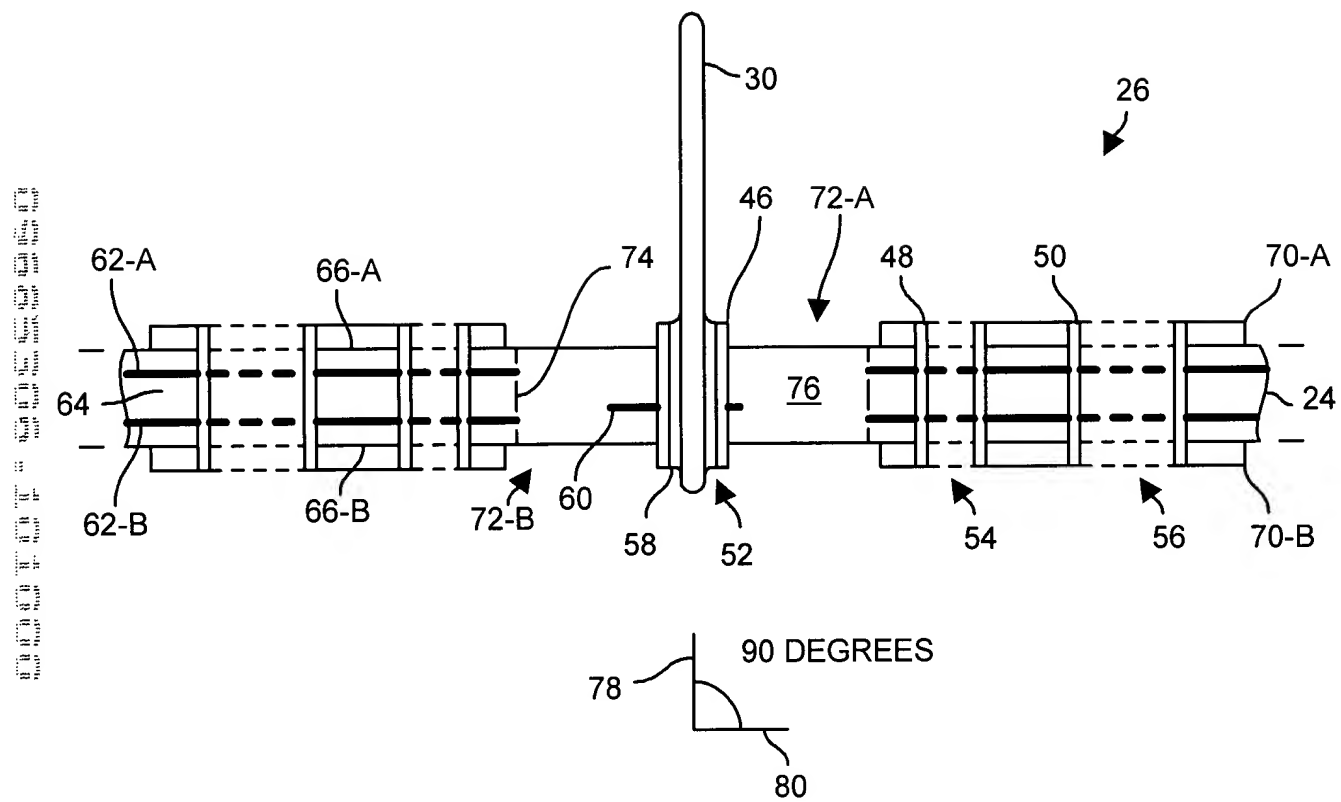


FIG. 3

FIG. 4 is a flowchart illustrating a method for providing a circuit board having a signal launch. The method includes providing a circuit board having a section of circuit board material and a signal launch that includes (i) a signal via, (ii) a first set of ground vias, and (iii) a second set of ground vias such that each of the first set of ground vias is disposed, from the signal via, a radial distance that is smaller than that of each of the second set of ground vias (e.g., form ground pads connecting all ground vias and solder signal pin in signal via such that signal pin extends perpendicularly from a plane of the circuit board section and the ground pad). The method also includes aligning a connector over the signal launch of the circuit board and moving the connector toward the signal launch until the connector makes electrical contact with the signal launch (e.g., insert end of signal pin into portion of the connector having a planar surface that is parallel to the plane of the circuit board section and the ground pad when a ground portion of the connector makes electrical contact with the ground vias of the signal launch, secure connector to signal launch using screws/bolts, etc.).

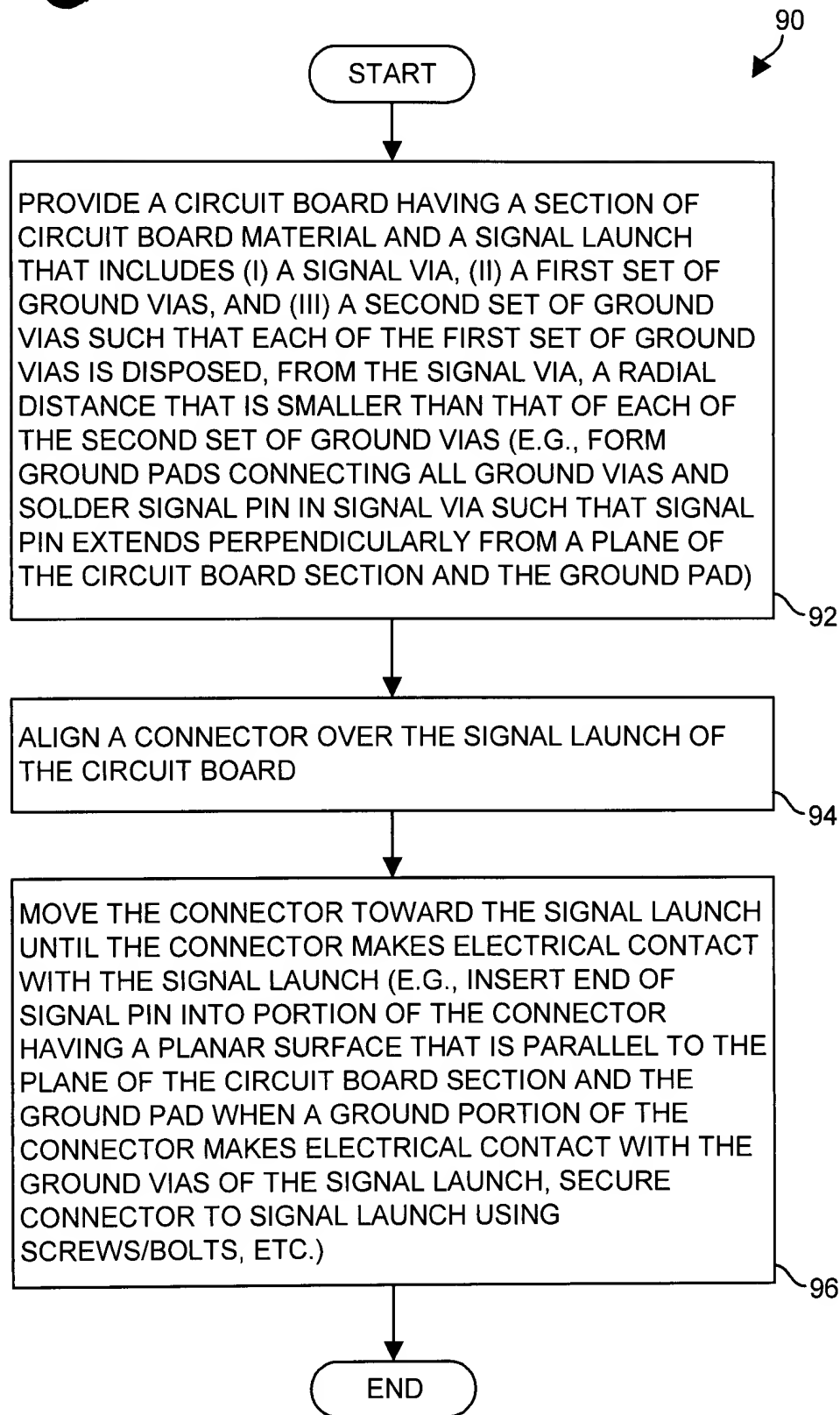


FIG. 4